

1-Mbit (128K x 8) Static RAM

Features

• Temperature Ranges

Commercial: 0°C to 70°CIndustrial: -40°C to 85°C

— Automotive-A: -40°C to 85°C

— Automotive-E: –40°C to 125°C

4.5V–5.5V operation

· CMOS for optimum speed/power

 Low active power (70 ns Commercial, Industrial, Automotive-A)

— 82.5 mW (max.) (15 mA)

 Low standby power (55/70 ns Commercial, Industrial, Automotive-A)

— 110 μW (max.) (15 μA)

• Automatic power-down when deselected

TTL-compatible inputs and outputs

Easy memory expansion with CE₁, CE₂, and OE options

 Available in Pb-free and non-Pb-free 32-pin (450 mil-wide) SOIC, 32-pin STSOP and 32-pin TSOP-I

Functional Description[1]

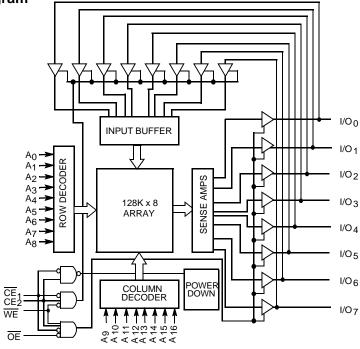
The CY62128BN is a high-performance CMOS static RAM organized as 128K words by 8 bits. Easy memory expansion is provided by an active LOW Chip Enable (CE₁), an active HIGH Chip Enable (CE₂), an active LOW Output Enable (OE), and tri-state drivers. This device has an automatic power-down feature that reduces power consumption by more than 75% when deselected.

Writing to the device is accompl<u>ished</u> by taking Chip Enable One ($\overline{\text{CE}}_1$) and Write Enable ($\overline{\text{WE}}$) inputs LOW and Chip Enable Two ($\overline{\text{CE}}_2$) input HIGH. Data on the eight I/O pins (I/O₀ through I/O₇) is then written into the location specified on the address pins (A_0 through A_{16}).

Reading from the device is accomplished by taking Chip Enable One ($\overline{\text{CE}_1}$) and Output Enable ($\overline{\text{OE}}$) LOW while forcing Write Enable ($\overline{\text{WE}}$) and Chip Enable Two ($\overline{\text{CE}_2}$) HIGH. Under these conditions, the contents of the memory location specified by the address pins will appear on the I/O pins.

The eight input/output pins (I/O $_0$ through I/O $_7$) are placed in a high-impedance state when the device is deselected (CE $_1$ HIGH or CE $_2$ LOW), the outputs are disabled (OE HIGH), or during a write operation (CE $_1$ LOW, CE $_2$ HIGH, and WE LOW).





Pin Configuration

| NC | V _{CC} |
|----------------------|--|
| A ₁₆ 2 31 | ⊢ |
| A12 | CE2 WE A13 A8 A9 A10 E10/07 1/06 (A10/08) 1/08 |

Note:

1. For best-practice recommendations, please refer to the Cypress application note "System Design Guidelines" on http://www.cypress.com.

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Product Portfolio

| | | | | | | Power Dissipation | | | |
|-------------|--------------|------|----------------------------|------|-------|--|------|---------------------|------|
| | | | V _{CC} Range (| V) | Speed | Operating, I _{CC} (mA) Standby, I _{SB2} (μ | | | |
| Product | | Min. | Typ. ^[2] | Max. | (ns) | Typ. ^[2] | Max. | Typ. ^[2] | Max. |
| CY62128BNLL | Commercial | 4.5 | 5.0 | 5.5 | 55 | 7.5 | 20 | 2.5 | 15 |
| | | | | | 70 | 6 | 15 | 2.5 | 15 |
| | Industrial | | | | 55 | 7.5 | 20 | 2.5 | 15 |
| | | | | | 70 | 6 | 15 | 2.5 | 15 |
| | Automotive-A | | | | 70 | 6 | 15 | 2.5 | 15 |
| | Automotive-E | | | | 70 | 6 | 25 | 2.5 | 25 |

Pin Configurations

| A ₁₁ □ 25 A ₉ □ 26 A ₈ □ 27 A ₁₃ □ 28 WE □ 29 CE ₂ □ 30 A ₁₅ □ 31 STSOP V _{CC} □ 32 Top View NC □ 1 O (not to scale) A ₁₆ □ 2 A ₁₄ □ 3 A ₁₂ □ 4 A ₇ □ 5 A ₆ □ 6 A ₅ □ 7 A ₄ □ 8 | 24 DE 23 DE 22 DE 21 DI/O7 20 DI/O6 19 DI/O4 17 DI/O4 16 DI/O2 14 DI/O1 13 DI/O1 13 DI/O1 14 DI/O1 15 DI/O1 17 DI/O1 18 DI/O2 19 DI/O3 10 DI/O3 10 DI/O3 11 DI/O3 11 DI/O3 11 DI/O3 12 DI/O3 11 DI/O3 12 DI/O3 13 DI/O4 14 DI/O3 15 DI/O4 16 DI/O3 17 DI/O3 18 DI/O4 19 DI/O3 19 | 10 12 3 4 5 6 7 8 9 10 11 12 13 14 15 16 16 17 18 19 19 19 19 19 19 19 19 19 19 | TSOP I Top View (not to scale) | 32 D DE 31 D CE1 30 D I/O ₇ 28 D I/O ₆ 27 D I/O ₆ 26 D I/O ₄ 25 D I/O ₁ 24 D I/O ₁ 23 D I/O ₂ 21 D A ₀ 19 D A ₁ 18 D A ₂ 17 D A ₃ |
|--|---|---|--------------------------------------|--|
|--|---|---|--------------------------------------|--|

Pin Definitions

| Input | A ₀ -A ₁₆ . Address Inputs | | | | | |
|---------------|--|--|--|--|--|--|
| Input/Output | I/O ₀ -I/O ₇ . Data lines. Used as input or output lines depending on operation | | | | | |
| Input/Control | WE . Write Enable, Active LOW. When selected LOW, a WRITE is conducted. When selected HIGH, a READ is conducted. | | | | | |
| Input/Control | CE ₁ . Chip Enable 1, Active LOW. | | | | | |
| Input/Control | CE ₂ . Chip Enable 2, Active HIGH. | | | | | |
| Input/Control | OE. Output Enable, Active LOW. Controls the direction of the I/O pins. When LOW, the I/O pins behave as outputs. When deasserted HIGH, I/O pins are tri-stated, and act as input data pins | | | | | |
| Ground | GND. Ground for the device | | | | | |
| Power Supply | V _{CC} . Power supply for the device | | | | | |

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^{2.} Typical values are included for reference only and are not tested or guaranteed. Typical values are an average of the distribution across normal production variations as measured at V_{CC} = 5.0V, T_A = 25°C, and t_{AA} = 70 ns.



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.) Storage Temperature-65°C to +150°C Ambient Temperature with Power Applied......-55°C to +125°C Supply Voltage on $\rm V_{CC}$ to Relative $\rm GND^{[3]}$ –0.5V to +7.0V DC Voltage Applied to Outputs in High-Z State $^{[3]}$ -0.5V to $\rm V_{CC}$ + 0.5V DC Input Voltage^[3].....-0.5V to V_{CC} + 0.5V Current into Outputs (LOW)20 mA

| Static Discharge Voltage(per MIL-STD-883, Method 3015) | .> 2001V |
|--|----------|
| Latch-up Current | > 200 mA |

Operating Range

| Range | Ambient Temperature (T _A) ^[4] | V _{CC} |
|--------------|---|-----------------|
| Commercial | 0°C to +70°C | 5V ± 10% |
| Industrial | -40°C to +85°C | |
| Automotive-A | -40°C to +85°C | |
| Automotive-E | -40°C to +125°C | |

Electrical Characteristics Over the Operating Range

| | | -55 | | | | | | | | |
|------------------|---|--|---------------------------|------|----------------------------|--------------------------|------|----------------------------|--------------------------|------|
| Parameter | Description | Test Condi | tions | Min. | Typ. ^[2] | Max. | Min. | Typ. ^[2] | Max. | Unit |
| V _{OH} | Output HIGH Voltage | $V_{CC} = Min., I_{OH} = -1.$ | 0 mA | 2.4 | | | 2.4 | | | V |
| V _{OL} | Output LOW Voltage | $V_{CC} = Min., I_{OL} = 2.1$ | mA | | | 0.4 | | | 0.4 | V |
| V _{IH} | Input HIGH Voltage | | | 2.2 | | V _{CC} + 0.3 | 2.2 | | V _{CC} + 0.3 | V |
| V _{IL} | Input LOW Voltage[3] | | | -0.3 | | 0.8 | -0.3 | | 0.8 | V |
| I _{IX} | Input Leakage Current | $GND \leq V_I \leq V_{CC}$ | Commercial/ Industrial | -1 | | +1 | -1 | | +1 | μА |
| | | | Automotive-A | | | | -1 | | +1 | μΑ |
| | | | Automotive-E | | | | -10 | | +10 | μΑ |
| I _{OZ} | Output Leakage Current | $\begin{array}{l} \text{GND} \leq \text{V}_{\text{I}} \leq \text{V}_{\text{CC}}, \\ \text{Output Disabled} \end{array}$ | Commercial/ Industrial | -1 | | +1 | -1 | | +1 | μА |
| | | | Automotive-A | | | | -1 | | +1 | μΑ |
| | | | Automotive-E | | | | -10 | | +10 | μΑ |
| I _{CC} | V _{CC} Operating Supply Current | | Commercial/ Industrial | | 7.5 | 20 | | 6 | 15 | mA |
| | | | Automotive-A | | | | | 6 | 15 | mA |
| | | | Automotive-E | | | | | 6 | 25 | mA |
| I _{SB1} | Automatic CE Power-down Current | $\begin{aligned} &\text{Max. V}_{\text{CC}}, \overline{\text{CE}}_1 \geq \text{V}_{\text{IH}} \\ &\text{or CE}_2 \leq \text{V}_{\text{IL}}, \end{aligned}$ | Commercial/ Industrial | | 0.1 | 2 | | 0.1 | 1 | mA |
| | —TTL Inputs | $V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$, $f = f_{MAX}$ | Automotive-A | | | | | 0.1 | 1 | mA |
| | | VIN S VIL, I - IMAX | Automotive-E | | | | | 0.1 | 2 | mA |
| I _{SB2} | Automatic CE Power-down Current | $\frac{\text{Ma}x. \ V_{CC},}{\text{CE}_1 \geq V_{CC} - 0.3V,}$ | Commercial/ Industrial | | 2.5 | 15 | | 2.5 | 15 | μА |
| | —CMOS Inputs | or $CE_2 \le 0.3V$, $V_{IN} \ge V_{CC} - 0.3V$, | Automotive-A | | | | | 2.5 | 15 | μΑ |
| | | or $V_{IN} \le V_{CC} - 0.3V$, $f = 0$ | Automotive-E | | | | | 2.5 | 25 | μΑ |

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^{3.} $V_{\rm IL}$ (min.) = -2.0V for pulse durations of less than 20 ns. 4. $T_{\rm A}$ is the "Instant On" case temperature.



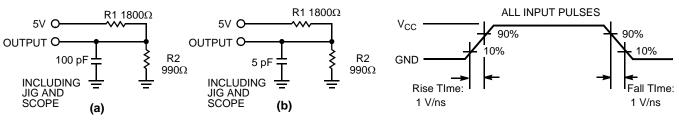
Capacitance^[5]

| Parameter | Description | Test Conditions | Max. | Unit |
|------------------|--------------------|---|------|------|
| C _{IN} | Input Capacitance | $T_A = 25^{\circ}C$, $f = 1 \text{ MHz}$, | 9 | pF |
| C _{OUT} | Output Capacitance | $V_{CC} = 5.0V$ | 9 | pF |

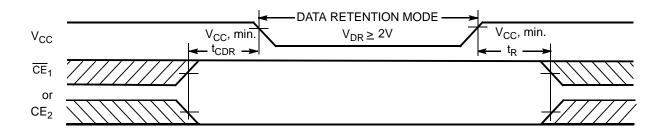
Thermal Resistance^[5]

| Parameter | Description | Test Conditions | 32 SOIC | 32 STSOP | 32 TSOP | Unit |
|---------------|---------------------------------------|---|---------|----------|---------|------|
| Θ_{JA} | ' | Test conditions follow standard test methods and procedures for measuring | 66.17 | 105.14 | 97.44 | °C/W |
| Θ_{JC} | Thermal Resistance (Junction to Case) | thermal impedance, per EIA / JESD51. | 30.87 | 14.09 | 26.05 | °C/W |

AC Test Loads and Waveforms



Data Retention Waveform



Data Retention Characteristics (Over the Operating Range)

| Parameter | Description | Conditions ^[6] | | | Тур. | Max. | Unit |
|-------------------|---|---|---|-----|------|------|------|
| V_{DR} | V _{CC} for Data Retention | | | 2.0 | | | V |
| I _{CCDR} | Data Retention Current | $\begin{array}{l} \frac{V_{CC} = V_{DR} = 2.0V,}{CE_1 \geq V_{CC} - 0.3V, \text{ or } CE_2 \leq 0.3V,}\\ V_{IN} \geq V_{CC} - 0.3V \text{ or, } V_{IN} \leq 0.3V \end{array}$ | Commercial/ Industrial Automotive-A | | 1.5 | 15 | μА |
| | | | Automotive-E | | 1.5 | 25 | μΑ |
| t _{CDR} | Chip Deselect to Data Retention Time | | | 0 | | | ns |
| t _R | Operation Recovery Time | | | 70 | | | ns |

Note:

^{5.} Tested initially and after any design or process changes that may affect these parameters.

^{6.} No input may exceed V_{CC} + 0.5V.

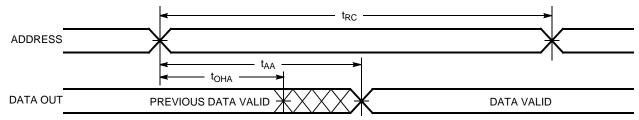


Switching Characteristics^[7] Over the Operating Range

| | | CY621 | 28BN-55 | CY6212 | | |
|-------------------|---|-------|---------|--------|------|------|
| Parameter | Description | Min. | Max. | Min. | Max. | Unit |
| READ CYCLE | | l. | · I | l | | |
| t _{RC} | Read Cycle Time | 55 | | 70 | | ns |
| t _{AA} | Address to Data Valid | | 55 | | 70 | ns |
| t _{OHA} | Data Hold from Address Change | 5 | | 5 | | ns |
| t _{ACE} | CE ₁ LOW to Data Valid, CE ₂ HIGH to Data Valid | | 55 | | 70 | ns |
| t _{DOE} | OE LOW to Data Valid | | 20 | | 35 | ns |
| t _{LZOE} | OE LOW to Low Z | 0 | | 0 | | ns |
| t _{HZOE} | OE HIGH to High Z ^[7, 9] | | 20 | | 25 | ns |
| t _{LZCE} | CE ₁ LOW to Low Z, CE ₂ HIGH to Low Z ^[9] | 5 | | 5 | | ns |
| t _{HZCE} | CE ₁ HIGH to High Z, CE ₂ LOW to High Z ^[8, 9] | | 20 | | 25 | ns |
| t _{PU} | CE ₁ LOW to Power-up, CE ₂ HIGH to Power-up | 0 | | 0 | | ns |
| t _{PD} | CE ₁ HIGH to Power-down, CE ₂ LOW to Power-down | | 55 | | 70 | ns |
| WRITE CYCL | E [10] | | | | | |
| t _{WC} | Write Cycle Time | 55 | | 70 | | ns |
| t _{SCE} | CE ₁ LOW to Write End, CE ₂ HIGH to Write End | 45 | | 60 | | ns |
| t _{AW} | Address Set-up to Write End | 45 | | 60 | | ns |
| t _{HA} | Address Hold from Write End | 0 | | 0 | | ns |
| t _{SA} | Address Set-up to Write Start | 0 | | 0 | | ns |
| t _{PWE} | WE Pulse Width | 45 | | 50 | | ns |
| t _{SD} | Data Set-up to Write End | 25 | | 30 | | ns |
| t _{HD} | Data Hold from Write End | 0 | | 0 | | ns |
| t _{LZWE} | WE HIGH to Low Z ^[9] | 5 | | 5 | | ns |
| t _{HZWE} | WE LOW to High Z ^[8, 9] | | 20 | | 25 | ns |

Switching Waveforms

Read Cycle No.1^[11, 12]



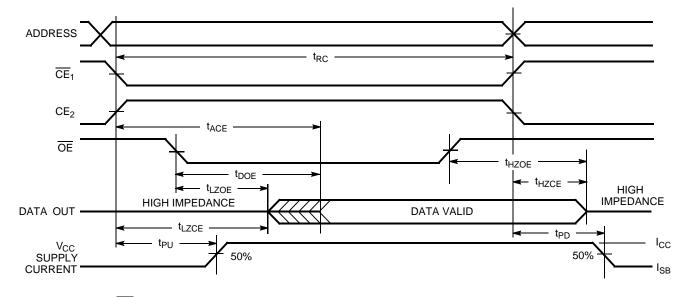
Notes:

- 7. Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 100-pF load capacitance.
- 8. thzoe, thzce, and thzwe are specified with a load capacitance of 5 pF as in (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
- 9. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZCE}, and t_{HZME} is less than t_{LZWE} or any given device.

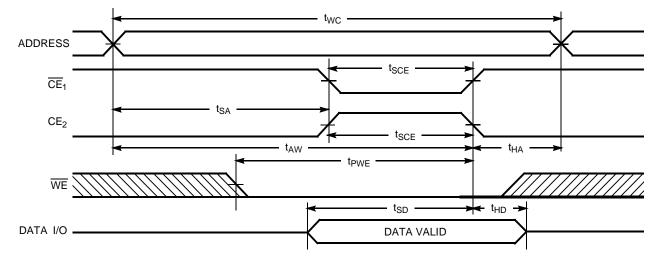
 10. The internal write time of the memory is defined by the overlap of Ct₂ LOW, Ct₂ HIGH, and WE LOW. Ct₂ and WE must be LOW and Ct₂ HIGH to initiate a write, and the transition of any of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.
- 11. <u>Device</u> is continuously selected. \overline{OE} , $\overline{CE}_1 = V_{IL}$, $CE_2 = V_{IH}$.
- 12. WE is HIGH for read cycle.

Switching Waveforms (continued)

Read Cycle No. 2 (OE Controlled)[12, 13]



Write Cycle No. 1 (CE₁ or CE₂ Controlled)^[14, 15]



Notes:

13. Address valid prior to or coincident with \overline{CE}_1 transition LOW and CE_2 transition HIGH.

14. Data I/O is high impedance if $\overline{OE} = V_{IH}$.

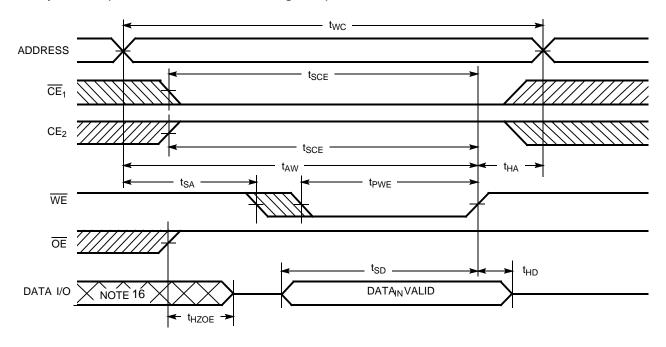
15. If \overline{CE}_1 goes HIGH or CE_2 goes LOW simultaneously with \overline{WE} going HIGH, the output remains in a high-impedance state.

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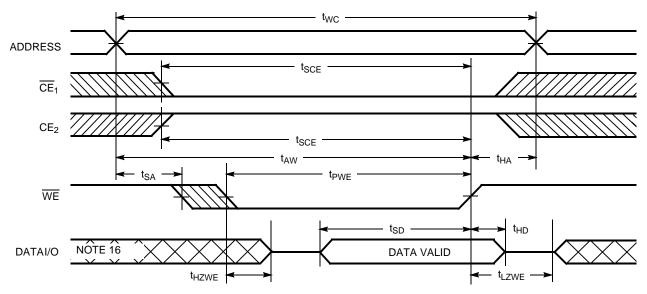


Switching Waveforms (continued)

Write Cycle No. 2 (WE Controlled, OE HIGH During Write)[14, 15]



Write Cycle No.3 (WE Controlled, OE LOW)[14, 15]



Note:

16. During this period the I/Os are in the output state and input signals should not be applied.



Truth Table

| CE ₁ | CE ₂ | OE | WE | I/O ₀ -I/O ₇ | Mode | Power |
|-----------------|-----------------|----|----|------------------------------------|----------------------------|----------------------------|
| Н | Х | Х | Х | High Z | Power-down | Standby (I _{SB}) |
| Х | L | Х | Х | High Z | Power-down | Standby (I _{SB}) |
| L | Н | L | Н | Data Out | Read | Active (I _{CC}) |
| L | Н | Х | L | Data In | Write | Active (I _{CC}) |
| L | Н | Н | Н | High Z | Selected, Outputs Disabled | Active (I _{CC}) |

Ordering Information

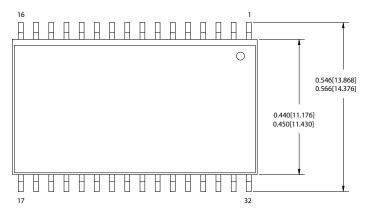
| Speed (ns) | Ordering Code | Package Diagram | Package Type | Operating Range |
|------------|--------------------|--------------------|-------------------------------|--------------------|
| 55 | CY62128BNLL-55SC | 51-85081 | 32-pin 450-Mil SOIC | Commercial |
| | CY62128BNLL-55SXC | 1 | 32-pin 450-Mil SOIC (Pb-Free) | |
| | CY62128BNLL-55SI | | 32-pin 450-Mil SOIC | Industrial |
| | CY62128BNLL-55SXI | 1 | 32-pin 450-Mil SOIC (Pb-Free) | |
| | CY62128BNLL-55ZAI | 51-85094 | 32-pin STSOP | |
| | CY62128BNLL-55ZAXI | 1 | 32-pin STSOP (Pb-Free) | |
| | CY62128BNLL-55ZI | 51-85056 | 32-pin TSOP Type I | |
| | CY62128BNLL-55ZXI | 1 | 32-pin TSOP Type I (Pb-Free) | |
| 70 | CY62128BNLL-70SC | 51-85081 | 32-pin 450-Mil SOIC | Commercial |
| | CY62128BNLL-70SXC | | 32-pin 450-Mil SOIC (Pb-Free) | |
| | CY62128BNLL-70ZC | 51-85056 | 32-pin TSOP Type I | |
| | CY62128BNLL-70ZXC | | 32-pin TSOP Type I (Pb-Free) | |
| | CY62128BNLL-70SI | 51-85081 | 32-pin 450-Mil SOIC | Industrial |
| | CY62128BNLL-70SXI | 7 | 32-pin 450-Mil SOIC (Pb-Free) | |
| | CY62128BNLL-70ZAI | 51-85094 | 32-pin STSOP | |
| | CY62128BNLL-70ZAXI | 7 | 32-pin STSOP (Pb-Free) | |
| | CY62128BNLL-70ZI | 51-85056 | 32-pin TSOP Type I | |
| | CY62128BNLL-70ZXI | | 32-pin TSOP Type I (Pb-Free) | |
| | CY62128BNLL-70ZXA | 51-85056 | 32-pin TSOP Type I (Pb-Free) | Automotive-A |
| | CY62128BNLL-70SXA | 51-85081 | 32-pin 450-Mil SOIC (Pb-Free) | |
| | CY62128BNLL-70SXE | 51-85081 | 32-pin 450-Mil SOIC (Pb-Free) | Automotive-E |
| | CY62128BNLL-70ZAXE | 51-85094 | 32-pin STSOP (Pb-Free) | |

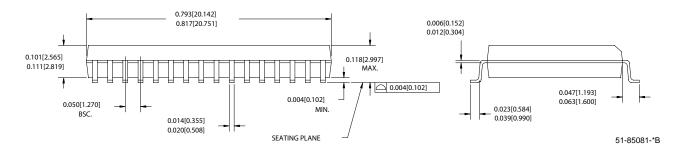
Please contact your local Cypress sales representative for availability of these parts



Package Diagrams

32-pin (450 Mil) Molded SOIC (51-85081)

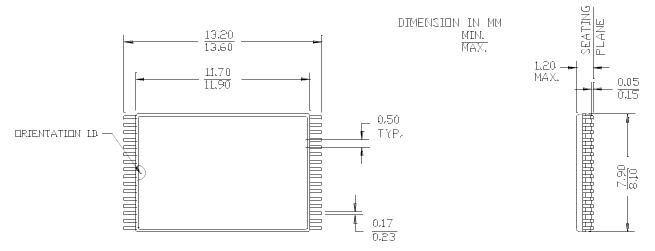


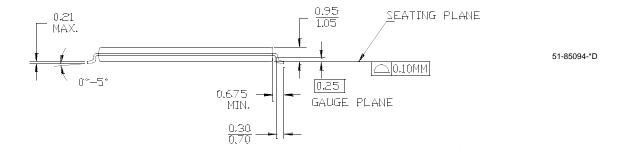




Package Diagrams (continued)

32-pin STSOP (8 x 13.4 mm) (51-85094)

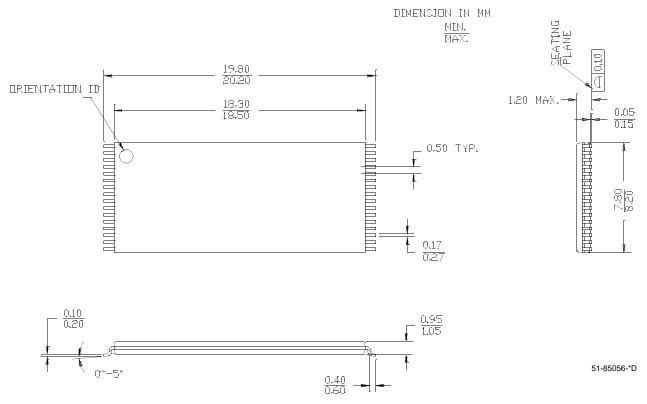






Package Diagrams (continued)

32-pin TSOP Type I (8 x 20 mm) (51-85056)



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[+] Feedback



Document History Page

| Document Title: CY62128BN MoBL [®] 1-Mbit (128K x 8) Static RAM Document Number: 001-06498 | | | | | | |
|---|---------|------------|--------------------|---|--|--|
| REV. | ECN NO. | Issue Date | Orig. of Change | Description of Change | | |
| ** | 426503 | See ECN | NXR | New Data Sheet | | |
| *A | 488954 | See ECN | NXR | Added Automotive product Removed RTSOP Package Updated ordering Information table | | |

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